

Application No.: 09/690,433

Docket No.: 22004-00003-US

**REMARKS**

Reconsideration of claims 1-17 and 19-24 is respectfully requested. Claims 1, 2, 6 and 15 are amended.

Applicants would like to thank the examiner for the helpful discussion in late September, 2003 regarding the rejected claims and the teachings of Cheng et al., US 5,901,038 (the '338 patent). Claims 1, 2 and 6 are amended to better define the ventilation openings as of sufficient dimension to "provide efficient cooling of the electronic module by allowing air to flow between the mother board and the electronic module and through the opening", as claimed. Presented in this manner, the claims overcome the examiner's concern that a pinhole or crack in a connector of the prior art could be broadly construed as a ventilation opening.

The rejection of claims 1-2, 6, 11, 15-17 and 20-21 under 35 U.S.C§103(a) as being unpatentable over Cheng et al. is respectfully traversed with respect to the amended claims. The '038 patent does not describe a connector that is used to connect an electronic module to a motherboard. Rather, the '038 patent describes a table-like mounting structure that is used to couple a power supply 140 to a motherboard 125. See, Abstract and Figs. 1-6, 11-12 and 14-16. There is no teaching or even any suggestion that the mounting structure can be used "as is" or modified to connect an electronic module to a motherboard. In fact, one skilled in the art would not look to the '038 patent to address the problem solved by applicants because the amount of heat generated by a power supply is substantially greater than that generated by an electronic module. Hence, the need for the attachment of heatsinks 1100/1200 to the mounting structure.

The Office Action takes the position that a power supply is a type of electronic module. That position is technically incorrect. As described on page 1 of the Application, an "electronic module comprises a card-like substrate, electronic chips, such as memory chips, [which can be] mounted on both ... surfaces of the substrate. See, also page 2 for a description of an electronic module with high performance chips used in notebook computers. Accordingly, Applicants respectfully request that the rejection be withdrawn.

In view of the above, each of the presently pending claims in this application is believed to be in condition for allowance.

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Please charge our Deposit Account No. 22-0185, under Order No. 22004-00003-US from which the undersigned is authorized to draw.

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Respectfully submitted,

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